ABSTRACT OF THE DISCLOSURE

A process for fabricating a semiconductor device is provided. The process integrates a cutting film process into the front-end of semiconductor process. The cutting film is directly formed on the curved surface of the micro-lens or a passivation layer is formed on the micro-lens before covering the passivation layer with the cutting film. In addition to micro-particle contamination due to sawing, the process is able to simplify chip packaging and reduce the size of a photosensitive module.